

ABSTRACT OF THE DISCLOSURE

This polyimide film is superior in heat resistance, rigidity and high frequency properties, is free of inconveniences due to curling even when various functional layers are laminated by heating, and is preferable as a substrate film superior in thermal degradation stability for electronic parts. This polyimide film has a planar orientation coefficient of 0.79-0.89 as measured by an X-ray diffraction method, a difference in the surface planar orientation degree between one surface thereof and the other surface thereof of not more than 2 and a curling degree of not more than 5%, which is obtained by imidation of a polyimide precursor film having a particular imidation rate.